

R8005ANJ FRG

V _{DSS}	800V
R _{DS(on)} (Max.)	2.1Ω
Ι _D	±5A
P _D	120W

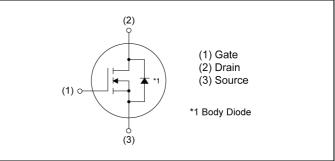
Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Parallel use is easy.
- 4) Pb-free plating ; RoHS compliant
- 5) AEC-Q101 qualified

●Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	R8005ANJ

Application

Switching Power Supply

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Symbol	Value	Unit
V _{DSS}	800	V
I _D *1	±5	А
۱ _{DP} *2	±10	А
V _{GSS}	±30	V
I _{AS} *3	2.5	А
E _{AS} *3	1.66	mJ
P _D	120	W
Tj	150	°C
T _{stg}	-55 to +150	°C
	$ \begin{array}{c} V_{DSS} \\ I_{D}^{*1} \\ I_{DP}^{*2} \\ V_{GSS} \\ I_{AS}^{*3} \\ E_{AS}^{*3} \\ P_{D} \\ T_{j} \\ $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

•Thermal resistance

Deremeter	Cymab al	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	1.04	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Deremeter	Sumbol	Conditions		Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		800	-	-	V	
		V _{DS} = 800V, V _{GS} = 0V					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μA	
		$T_j = 125^{\circ}C$	-	-	-		
Gate - Source leakage current	I _{GSS}	V_{GS} = ±30V, V_{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	V _{DS} = 10V, I _D = 1mA	3.0	-	5.0	V	
		V _{GS} = 10V, I _D = 2.5A					
Static drain - source on - state resistance	R _{DS(on)} *4	$T_j = 25^{\circ}C$	-	1.6	2.1	Ω	
		$T_j = 125^{\circ}C$	-	3.8	-		
Gate resistance	R _G	f = 1MHz, open drain	-	7.6	-	Ω	



•Electrical characteristics (T_a = 25°C)

Devenuetor	Current of	Conditions		Linit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	$ Y_{fs} ^{*4}$ V _{DS} = 10V, I _D = 2.5A		1.0	-	-	S	
Input capacitance	C _{iss}	C _{iss} V _{GS} = 0V		500	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	250	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	25	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 400$ V, V_{GS} = 10V	-	25	-		
Rise time	t _r *4	I _D = 2.5A	-	30	-	20	
Turn - off delay time	t _{d(off)} *4	R _L ≃ 162Ω	-	50	-	ns	
Fall time	t _f *4	R _G = 10Ω	-	27	-		

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Cumph of	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*4} $V_{DD} \simeq 400V$		-	20	-	
Gate - Source charge	Q _{gs} *4	Q_{gs}^{*4} I _D = 5A		5	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	11	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 400V$, $I_D = 5A$	-	7.4	-	V

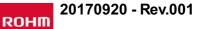
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*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \simeq 500µH, V_{DD}=50V, R_G=25 Ω , starting T_j=25°C

*4 Pulsed

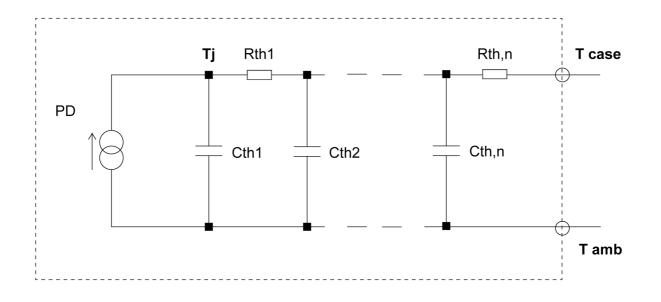


•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Sumbol	Conditions		Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	ا _S *1	T - 25°0	-	-	5	А	
Pulse forward current	ا _{SP} *2	T _C = 25°C	-	-	10	А	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 5A	-	-	1.5	V	
Reverse recovery time	t _{rr} *4		-	330	-	ns	
Reverse recovery charge	Q _{rr} *4	I _S = 5A, V _{GS} = 0V di/dt = 100A/µs	-	2.64	-	μC	
Peak reverse recovery current	۲ _{rrm} *4		-	16	-	А	

• Typical transient thermal characteristics

Symbol	Value	Unit	Symbol	Value	Unit
R _{th1}	0.771		C_{th1}	0.003718	
R _{th2}	7.231	K/W	C_{th2}	0.3051	Ws/K
R _{th3}	66.01		$C_{\text{th}3}$	0.8206	





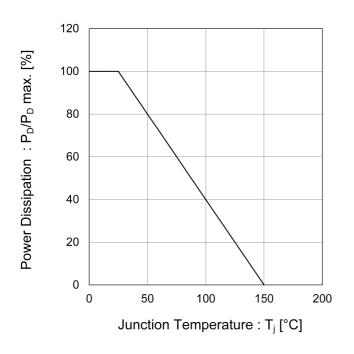


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

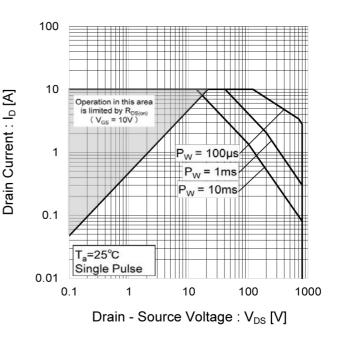
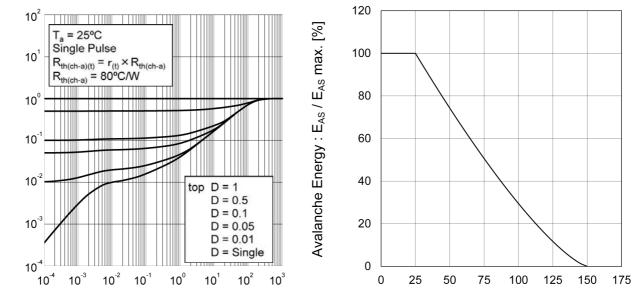


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Pulse Width : PW [s]

Fig.4 Avalanche Energy Derating Curve vs. Junction Temperature



Junction Temperature : Tj [ºC]

Normalized Transient Thermal Resistance : $r_{\left(t\right)}$





•Electrical characteristic curves

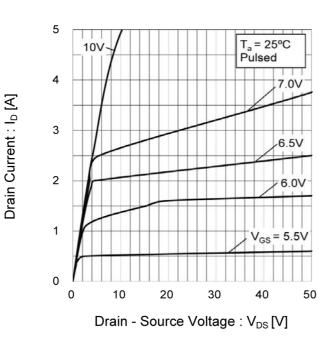
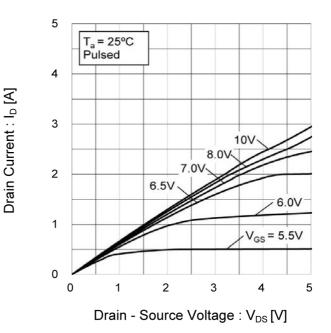


Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)





• Electrical characteristic curves

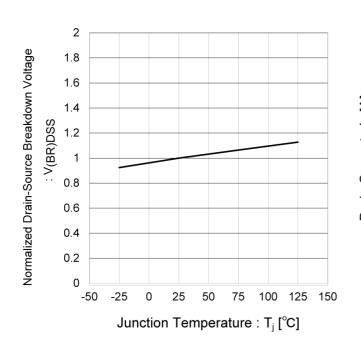


Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

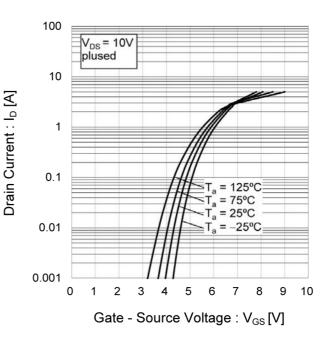
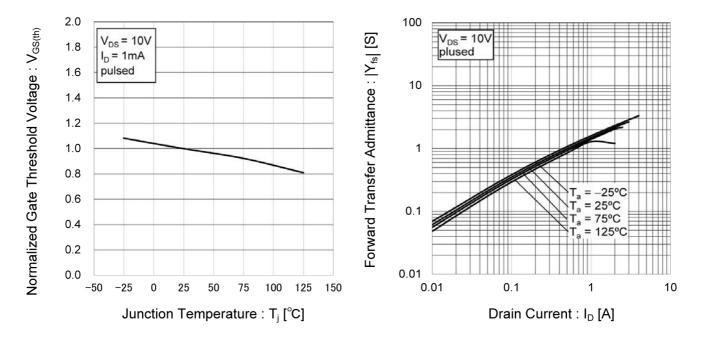


Fig.8 Typical Transfer Characteristics

Fig.	9 Normalized Gate Threshold Voltage
VS.	Junction Temperature

Fig.10 Forward Transfer Admittance vs. Drain Current





Electrical characteristic curves

Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

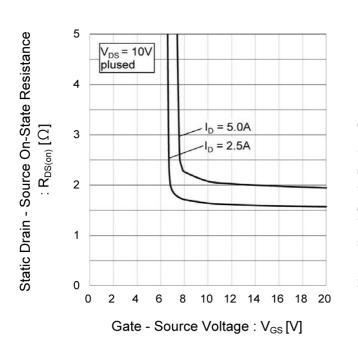


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

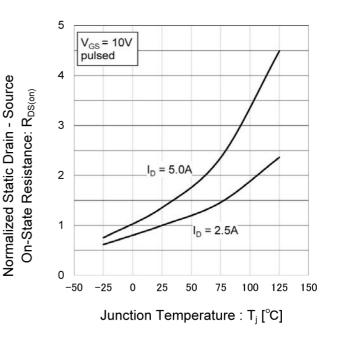
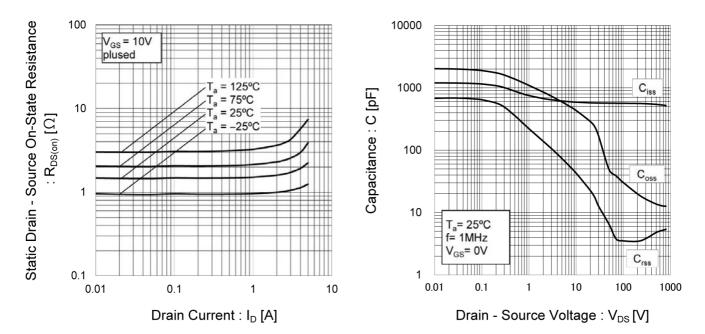


Fig.14 Typical Capacitance vs. Drain -Source Voltage





• Electrical characteristic curves

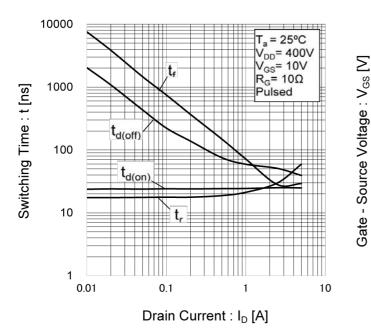


Fig.15 Switching Characteristics

Fig.16 Dynamic Input Characteristics

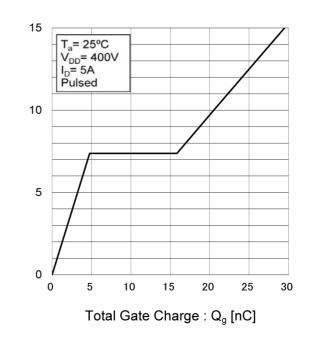
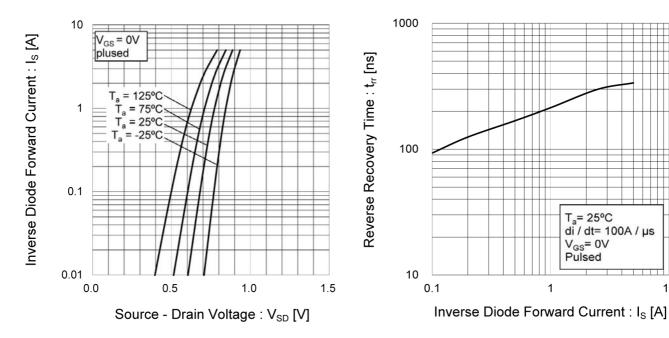


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage







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Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

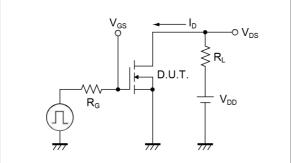


Fig.2-1 Gate Charge Measurement Circuit

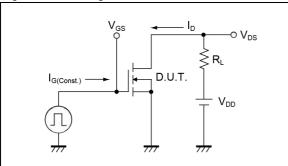


Fig.3-1 Avalanche Measurement Circuit

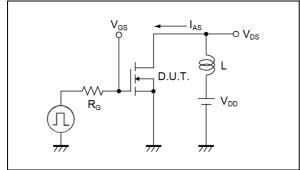
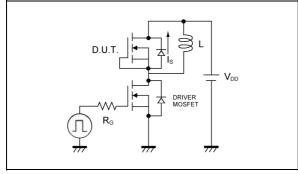


Fig.4-1 trr Measurement Circuit



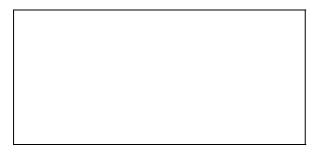


Fig.1-2 Switching Waveforms

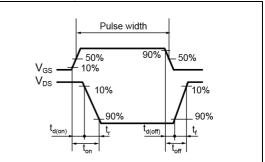


Fig.2-2 Gate Charge Waveform

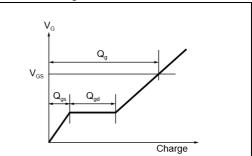


Fig.3-2 Avalanche Waveform

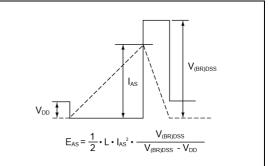
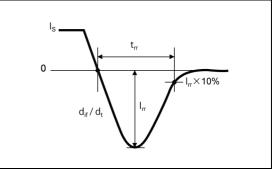
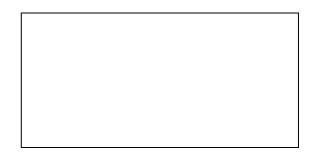


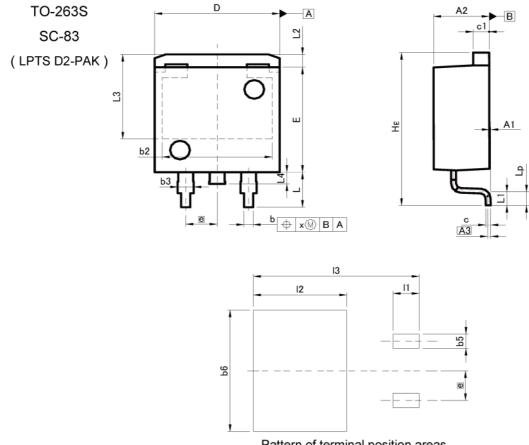
Fig.4-2 trr Waveform







Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90		350
b3	1.14	1.44	0.045	0.057
C	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
e	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.0	947
L2	1.	10	0.0)43
L3	7.	7.25		285
L4	1.	00	0.0)39
Lp	0.90	1.50	0.035	0.059
x	7 2	0.25	-	0.010
	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b5	.	1.23	-	0.049
b6		10.40		0.409
11	<u> </u>	2.10	<u>, 12</u>	0.083
12		7.55	1. 1.	0.297
13	-	13.40	-	0.528

Dimension in mm/inches





Notice

Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Ap	oplications
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JAPAN	USA	EU	CHINA
CLASSII	CLASSI	CLASS II b	CLASSⅢ
CLASSIV		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:

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[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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